

Aliases (C0603C104J3RAC7867) SMD Comm X7R, Ceramic, 0.1 uF, 5%, 25 VDC, X7R, SMD, MLCC, Temperature Stable, Class II, 0603, 0.5 mm



General Information				
Series	SMD Comm X7R			
Style	SMD Chip			
Description	SMD, MLCC, Temperature Stable, Class II			
Features	Temperature Stable, Class II			
RoHS	Yes			
Termination	Tin			
Marking	No			
AEC-Q200	No			
Typical Component Weight	7.3 mg			
Shelf Life	78 Weeks			
MSL	1			

0.1 uF

Dimensions	
Chip Size	0603
L	1.6mm +/-0.15mm
W	0.8mm +/-0.15mm
Т	0.8mm +/-0.15mm
S	0.5mm MIN
В	0.35mm +/-0.15mm

••	
Т	0.8mm +/-0.15mm
S	0.5mm MIN
В	0.35mm +/-0.15mm
Packaging Specifications	

Packaging

Packaging Quantity

	1.6mm +/-0.15mm	Measurement Condition	1 kHz 1.0Vrms
	0.8mm +/-0.15mm	Tolerance	5%
	0.8mm +/-0.15mm	Voltage DC	25 VDC
	0.5mm MIN	Dielectric Withstanding Voltage	62.5 VDC
	0.35mm +/-0.15mm	Temperature Range	-55/+125°C
		Temp. Coefficient	X7R
tions	T&R, 180mm, Paper Tape	Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vrms
	4000	Dissipation Factor	3.5% 1 kHz 1.0Vrms
		Aging Rate	3% Loss/Decade Hour: Referee Time is 48 Hours

Specifications

Capacitance

l	Dielectric Withstanding Voltage	62.5 VDC	
-0.15mm	Temperature Range	-55/+125°C	
	Temp. Coefficient	X7R	
m, Paper Tape	Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vrms	
	Dissipation Factor	3.5% 1 kHz 1.0Vrms	
	Aging Rate	3% Loss/Decade Hour: Referee Time is 48 Hours	
	Insulation Resistance	5 GOhms	

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

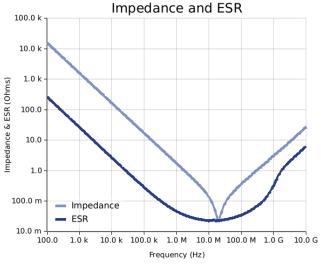
Generated 05/21/2025 © 2006 - 2025 YAGEO

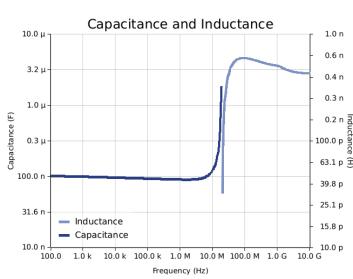


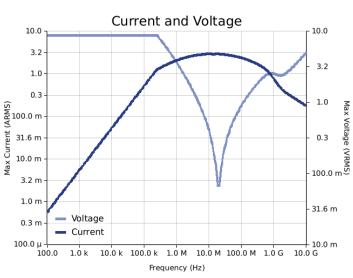
Aliases (C0603C104J3RAC7867) SMD Comm X7R, Ceramic, 0.1 uF, 5%, 25 VDC, X7R, SMD, MLCC, Temperature Stable, Class II, 0603, 0.5 mm

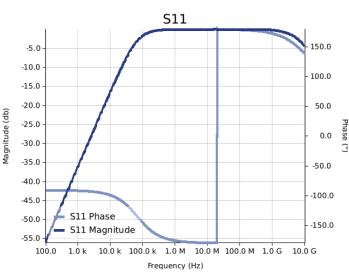
Simulations

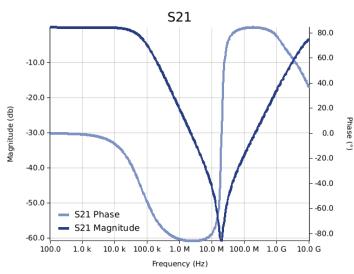
For the complete simulation environment please visit K-SIM.

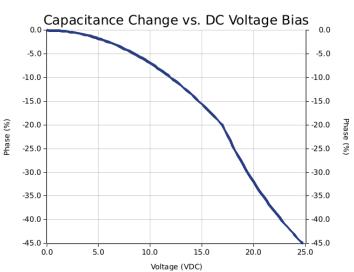








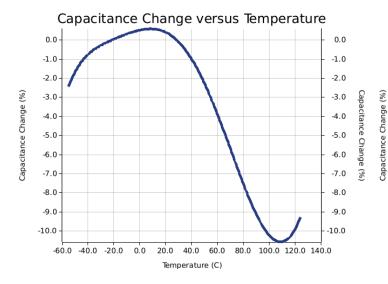


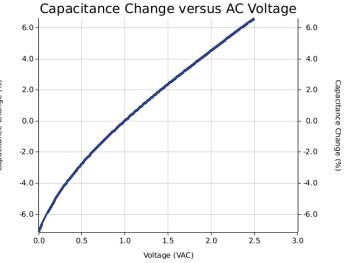


Generated 05/21/2025 © 2006 - 2025 YAGEO



Aliases (C0603C104J3RAC7867) SMD Comm X7R, Ceramic, 0.1 uF, 5%, 25 VDC, X7R, SMD, MLCC, Temperature Stable, Class II, 0603, 0.5 mm





Generated 05/21/2025 © 2006 - 2025 YAGEO



Aliases (C0603C104J3RAC7867) SMD Comm X7R, Ceramic, 0.1 uF, 5%, 25 VDC, X7R, SMD, MLCC, Temperature Stable, Class II, 0603, 0.5 mm

These are simulations.

This is not a specification!

The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

The responses shown do not represent a specified or implied maximum capability of the device for all applications.

- The ESR used for ripple "Ripple Current/Voltage vs. Frequency" plots is the ESR at ambient temperature.

- The ESR used for ripple Ripple Currenty votage vs. rrequency plots is unleast at an interact temperature.
 The ESR in the "Temperature Rise vs. Ripple Current" plots is adjusted to each incremental temperature rise before the power and ripple current is calculated.
 The effects shown herein are based on measured data from a multiple part sample of the parts in question.
 Ripple capability of this device will be factored by thermal resistance (Rth) created by circuit traces (addi affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.
 The peak voltages generated in the "Temperature Rise vs. Combined Ripple Currents" plot are calculated for each frequency and are not combined with voltages
- generated at any other harmonics.

 Please consult with the catalog or field applications engineer for maximum capability of the device in specific applications.

All product information and data (collectively, the "Information") are subject to change without notice.

KEMET K-SIM is designed to simulate behavior of components with respect to frequency, ambient temperature, and DC bias levels. The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation effects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

All Information given herein is believed to be accurate and reliable, but is presented without guarantee, warranty, or responsibility of any kind, expressed or implied. Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute – and we specifically disclaim – any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

If you have any questions please contact K-SIM.

Generated 05/21/2025 © 2006 - 2025 YAGEO